

DESCRIPTION

The MXN3060 uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

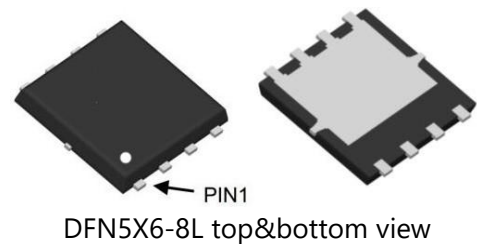
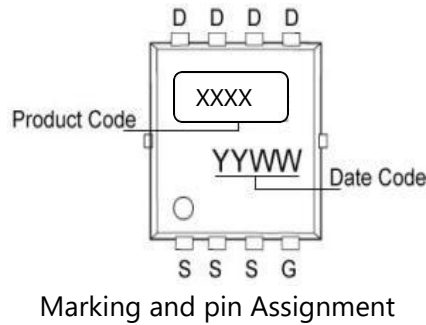
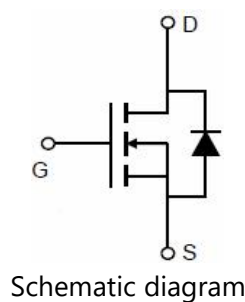
GENERAL FEATURES

- $V_{DS}=30V$, $I_D=60A$
 $R_{DS(ON)}(Typ.)=6.0m\Omega$ @ $V_{GS}=4.5V$
 $R_{DS(ON)}(Typ.)=5.0m\Omega$ @ $V_{GS}=10V$
- Low density cell design
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation

APPLICATION

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

PINOUT



ORDERING INFORMATION

Part Number	Storage Temperature	Package	Devices Per Reel
MXN3060	-55°C to 150°C	DFN5X6-8L	5000

ABSOLUTE MAXIMUM RATINGS($T_C=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	60	A
Pulsed Drain Current ^(Note1)	I_{DM}	150	A
Maximum Power Dissipation	P_D	42	W
Derating factor		0.5	W/°C
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

THERMAL RESISTANCE

Thermal Resistance, Junction-to-Case ^(Note2)	$R_{\theta JC}$	3.0	°C/W
---	-----------------	-----	------

Note 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

Note 2. Surface Mounted on FR4 Board, $t \leq 10$ sec.


ELECTRICAL CHARACTERISTICS ($T_C=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
-----------	--------	------------	-----	-----	-----	------

Off Characteristics

Drain-Source Breakdown Voltage	BV_{DS}	$V_{GS}=0V, I_D=250\mu A$	30	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=24V, V_{GS}=0V$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	± 100	nA

On Characteristics (Note 3)

Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.4	2.0	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=4.5V, I_D=20A$	-	6.0	9.0	m Ω
		$V_{GS}=10V, I_D=20A$	-	5.0	6.5	m Ω
Forward Transconductance	g_{FS}	$V_{DS}=5V, I_D=20A$	-	57	-	S

Dynamic Characteristics (Note 4)

Input Capacitance	C_{iss}	$V_{DS}=15V, V_{GS}=0V,$ $F=1.0MHz$	-	1950	-	pF
Output Capacitance	C_{oss}		-	310	-	pF
Reverse Transfer Capacitance	C_{rss}		-	240	-	pF

Switching Characteristics (Note 4)

Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=15V, R_L=15\Omega,$ $V_{GS}=10V, R_G=2.5\Omega$	-	8.1	-	nS
Turn-on Rise Time	t_r		-	8.6	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	30	-	nS
Turn-Off Fall Time	t_f		-	9	-	nS
Total Gate Charge	Q_g	$V_{DS}=15V, I_D=20A,$ $V_{GS}=10V$	-	37	-	nC
Gate-Source Charge	Q_{gs}		-	4.8	-	nC
Gate-Drain Charge	Q_{gd}		-	11	-	nC

Drain-Source Diode Characteristics

Diode Forward Voltage (Note 3)	V_{SD}	$V_{GS}=0V, I_S=20A$	-	-	1.2	V
Diode Forward Current (Note 2)	I_S		-	-	60	A
Reverse Recovery Time	t_{rr}	$T_J = 25^\circ\text{C}, I_F = 20A$ $di/dt = 100A/\mu s$ (Note 3)	-	26	-	nS
Reverse Recovery Charge	Q_{rr}		-	34	-	nC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

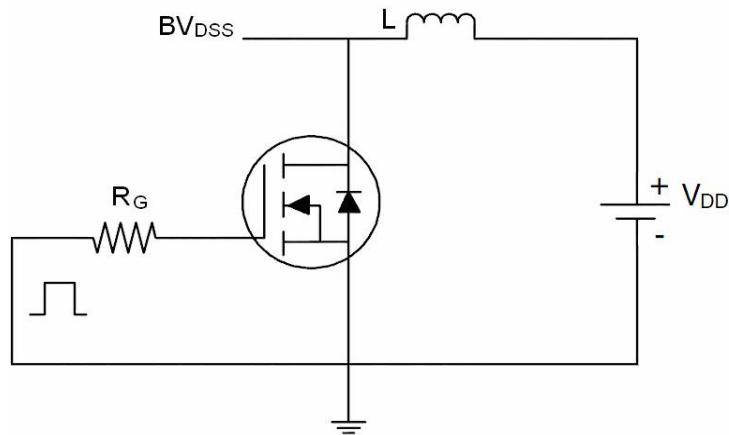
Note 2. Surface Mounted on FR4 Board, $t \leq 10$ sec.

Note 3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.

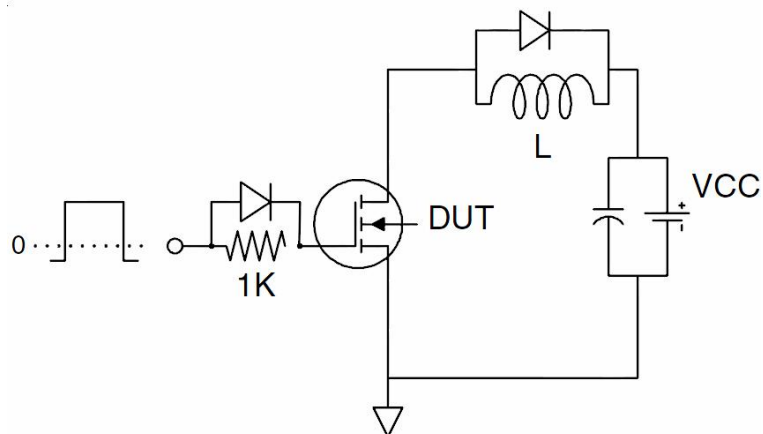
Note 4. Guaranteed by design, not subject to product.

TEST CIRCUIT

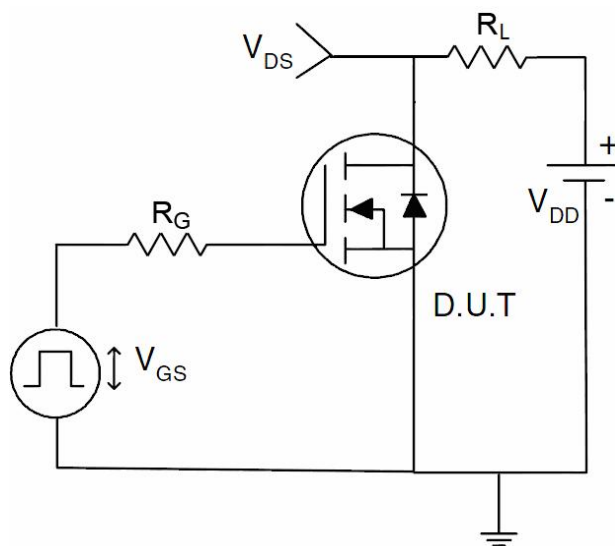
1. EAS Test Circuit



2. Gate Charge Test Circuit



3. Switch Time Test Circuit





TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 1. Output Characteristics

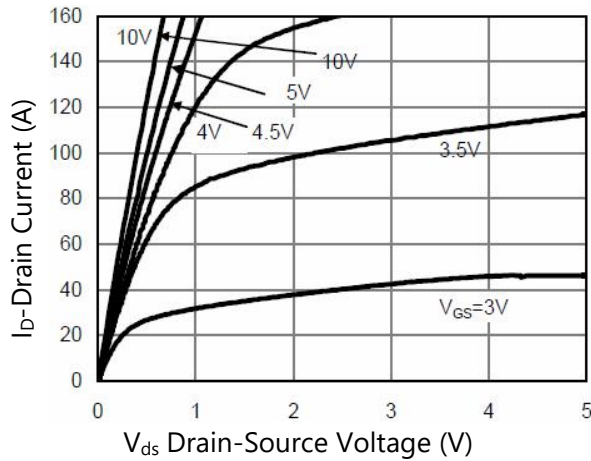


Figure 2. Transfer Characteristics

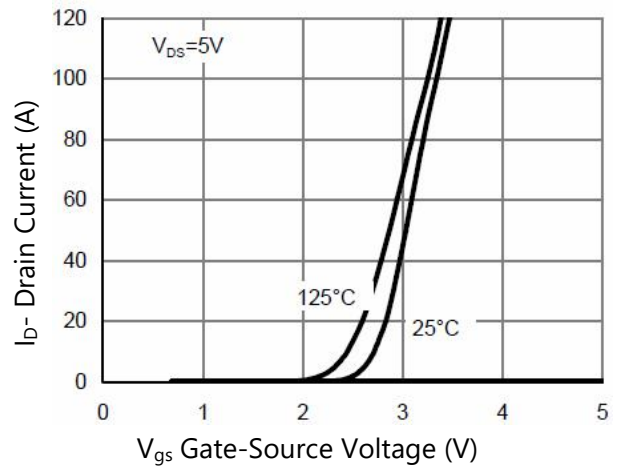


Figure 3. Rds(on) vs Drain Current

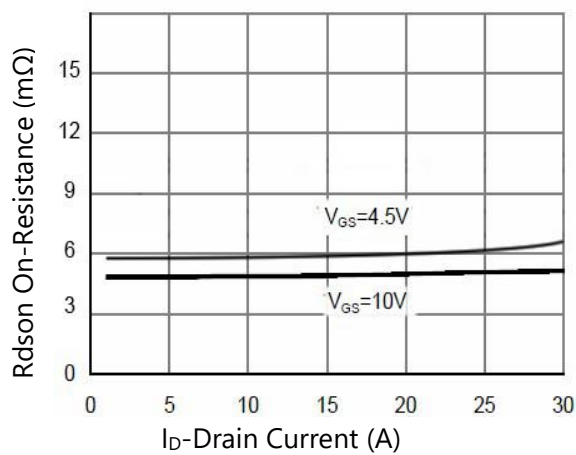


Figure 4. Rds(on) vs Junction Temperature

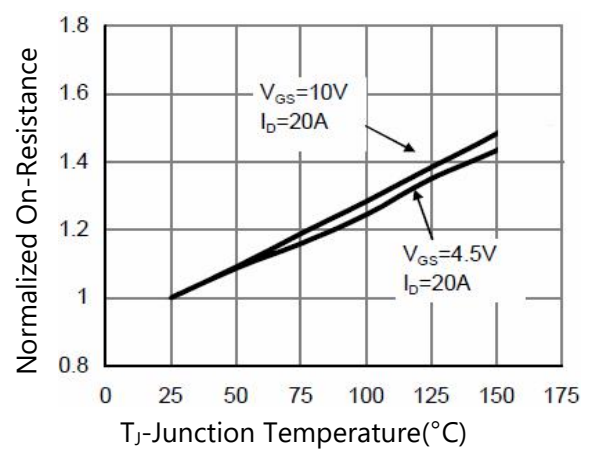


Figure 5. Gate Charge

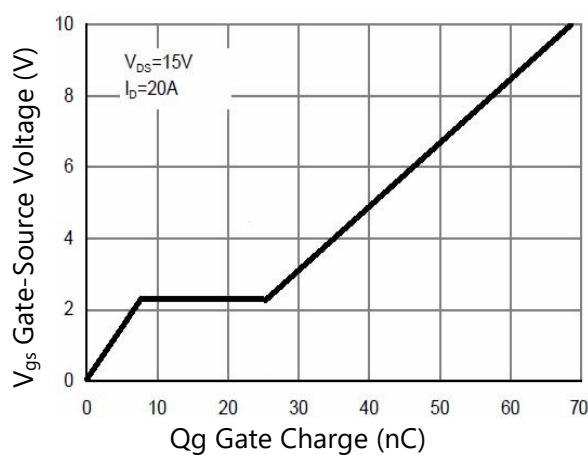
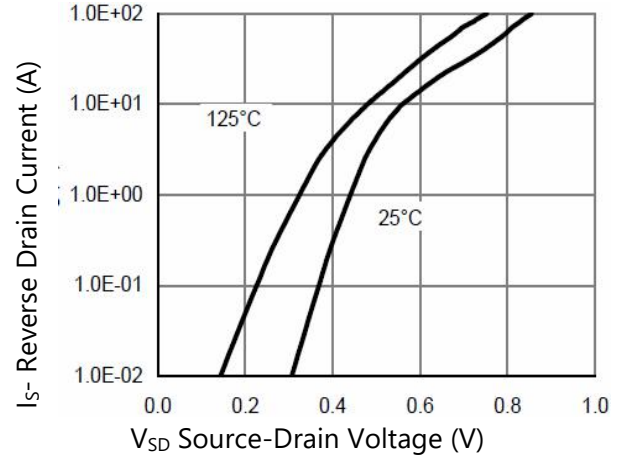


Figure 6. Source- Drain Diode Forward





TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 7. Capacitance vs V_{DS}

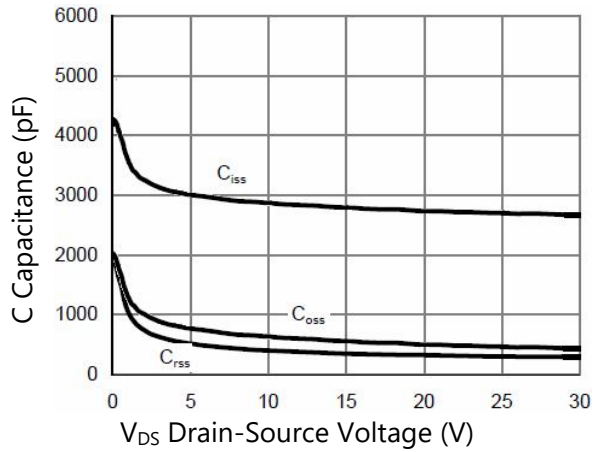


Figure 8. $R_{DS(on)}$ vs Gate-Source Voltage

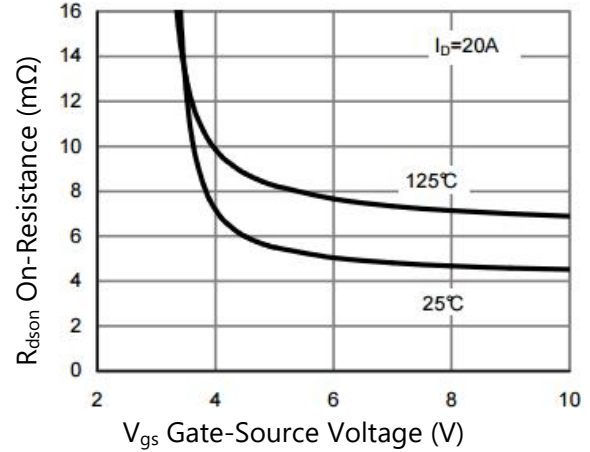


Figure 9. Current- Junction Temperature

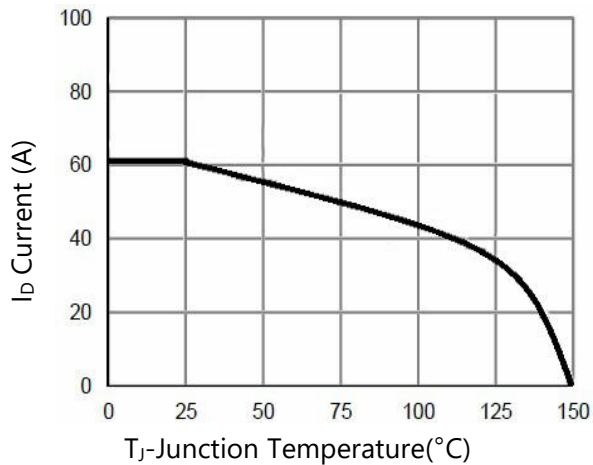


Figure 10. Safe Operation Area

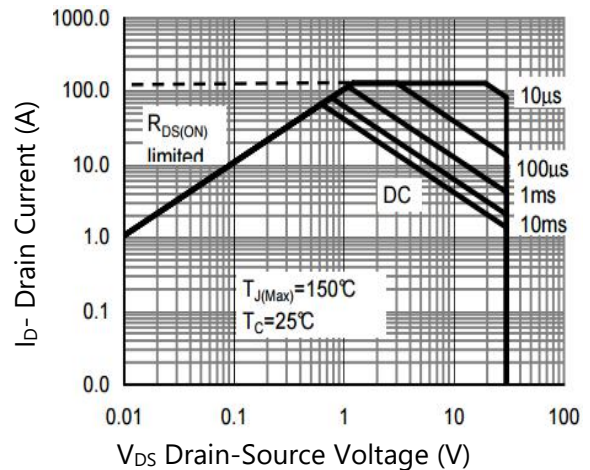
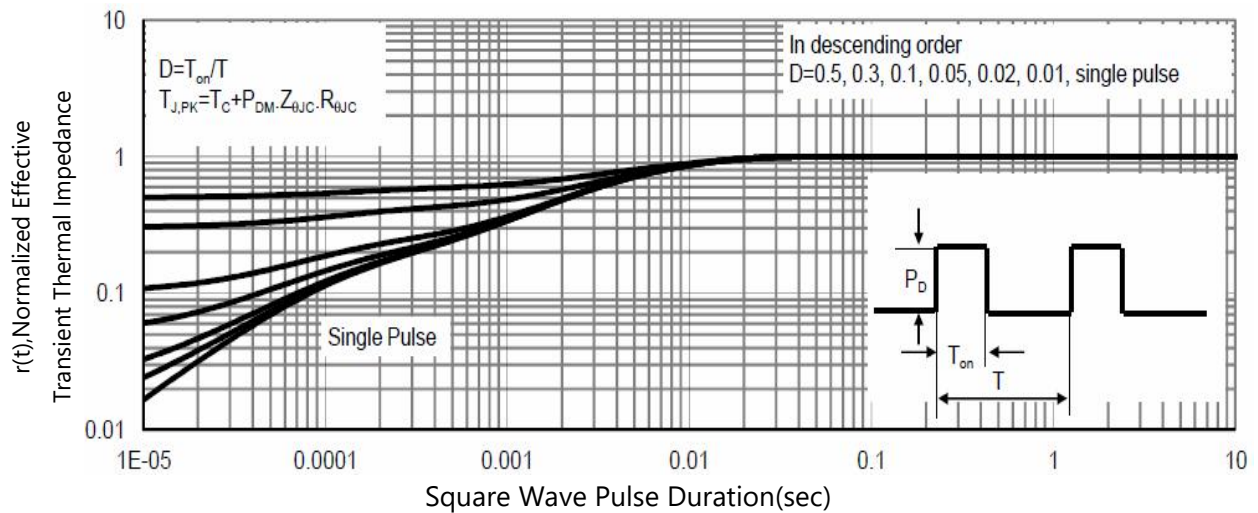


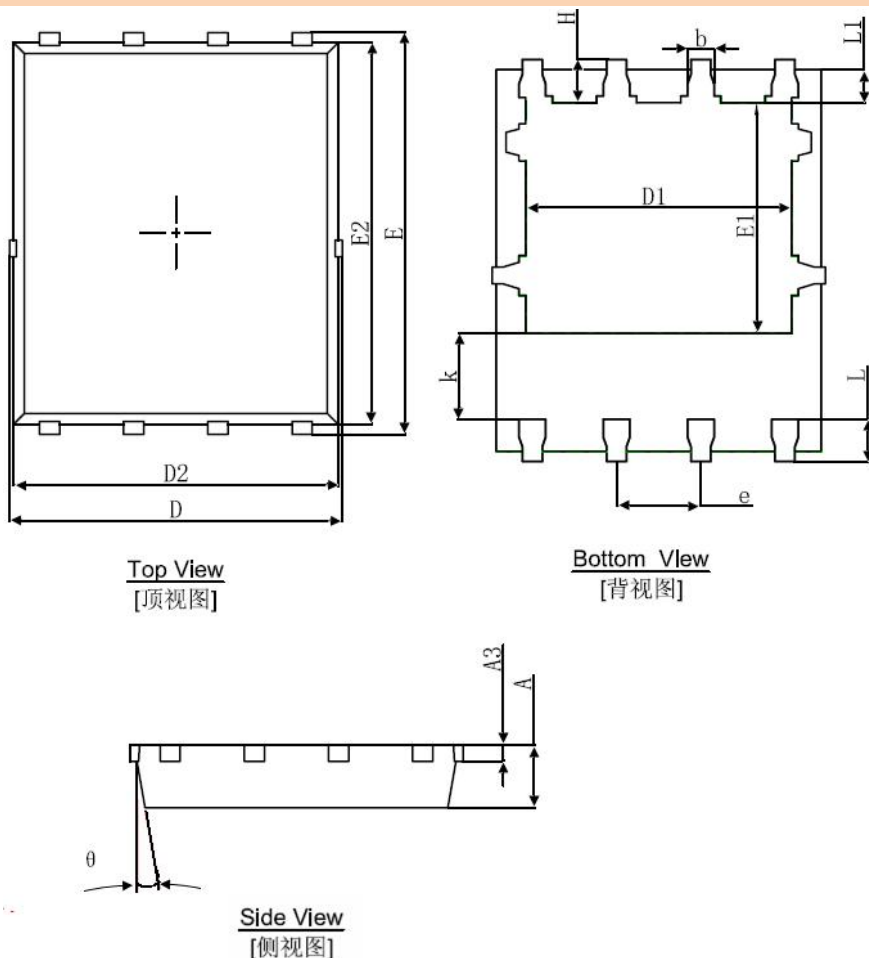
Figure 11. Normalized Maximum Transient Thermal Impedance





PACKAGE INFORMATION

DFN5X6-8L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254REF.		0.010REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	8°	12°	8°	12°